# **Panasonic**



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Partnering to go beyond.

Electronic Materials
Panasonic Corporation

# **Specification**

Liquid encapsulant materials

# CV5390HS

TECHNICAL INFORMATION
This is one component epoxy

### **TYPICAL PROPERTIES**

Properties	Unit	Data	Test Method
Viscosity(25degC)	Pa*s	3	KES 0171
Thixo,index	-	1.0	KES 0170
Gelation time	sec	15	KES 0175

#### **TYPICAL CURED PROPERTIES**

Test piece curing Conditions: 80degC 60 minutes

Properties	Unit	Data	Test Method
Glass Trans. Temp.	degC	60	KES 0109
C.T.E.	×10 <sup>-5</sup> /degC	6.0	KES 0109
Flexural Modulus	GPa	2.5	KES 0125

### **ATTENTION TO STORAGE**

- #Stored compound must be thawed before use. Warm at room temperature until no longer cool to touch (about 1-2hrs).
- #Please use up the material within 24 hrs.
- #Compound must be stored in the cool condition with sealing.(store under -20degC in refrigerator)
- #Please keep material under -20degC after receiving product.

### ATTENTION TO HANDLING

- #Please avoid direct contact with this product by wearing gloves, protecting gears, etc.
- #Prevent frequent skin contact. If contact occurs, wash immediately with soap and water.

Not for product specifications

The technical data contained herein are intended as reference only.

\* The data in the above table are not guaranteed values.



# ++ Before purchase ++

# [Notes before you use]

- Please verify the suitability and fitness for intended application by quality testing, evaluation or other means at your own option before any adoption, use or change of use conditions of a product listed in the datasheet.
- •We would like to have a delivery specifications mutually agreed for the product that you have decided to use. The agreements defined in the delivery specifications are assigned higher priority.
- Please note that specifications and external design are subject to change for product improvement without notice.
- For details on products in the datasheet, please contact your distributor or our sales department.

# **[Safety Information]**

- •Before using the product, please read the delivery specifications carefully or contact the distributor from which you purchased the product or our sales department in order to use the product correctly.
- •The products in the datasheet are Semiconductor encapsulation materials for electronic and electrical devices. Please do not use them for other than specified use.

### Please Contact us of more

### [Plant &

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